

SOT1968-1

LFBGA196, low profile fine pitch ball grid array, 196 terminals, 0.8 mm pitch, 12 mm x 12 mm x 1.37 mm body

12 April 2018

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA196
Package type industry code	LFBGA196
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-3-2018
Manufacturer package code	98ASA01198D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	12	-	mm
E	package width	-	-	12	-	mm
A	seated height	-	-	1.37	-	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	196	-	A/A



2. Package outline

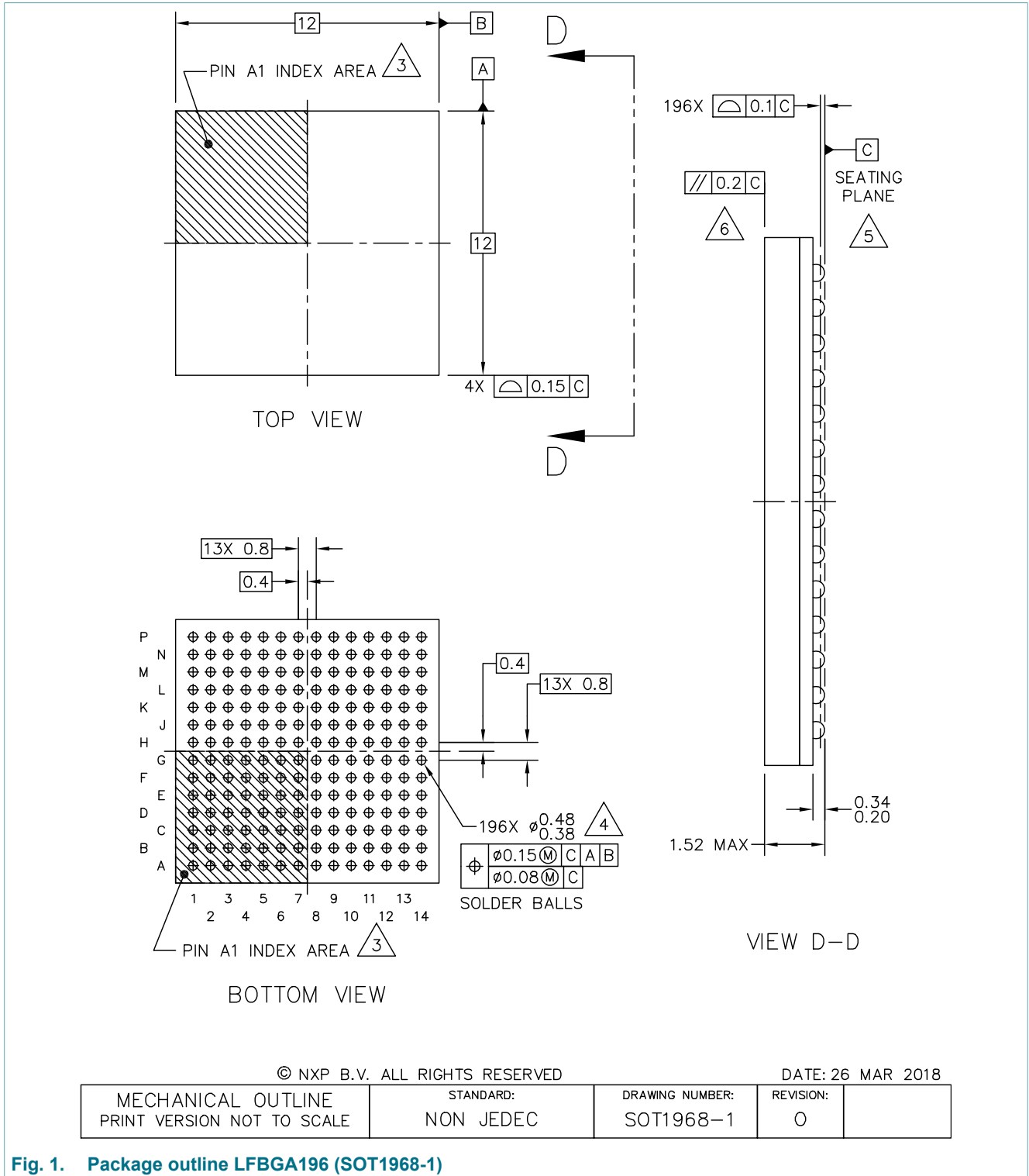


Fig. 1. Package outline LFBGA196 (SOT1968-1)

LFBGA196, low profile fine pitch ball grid array, 196 terminals, 0.8 mm pitch, 12 mm x 12 mm x 1.37 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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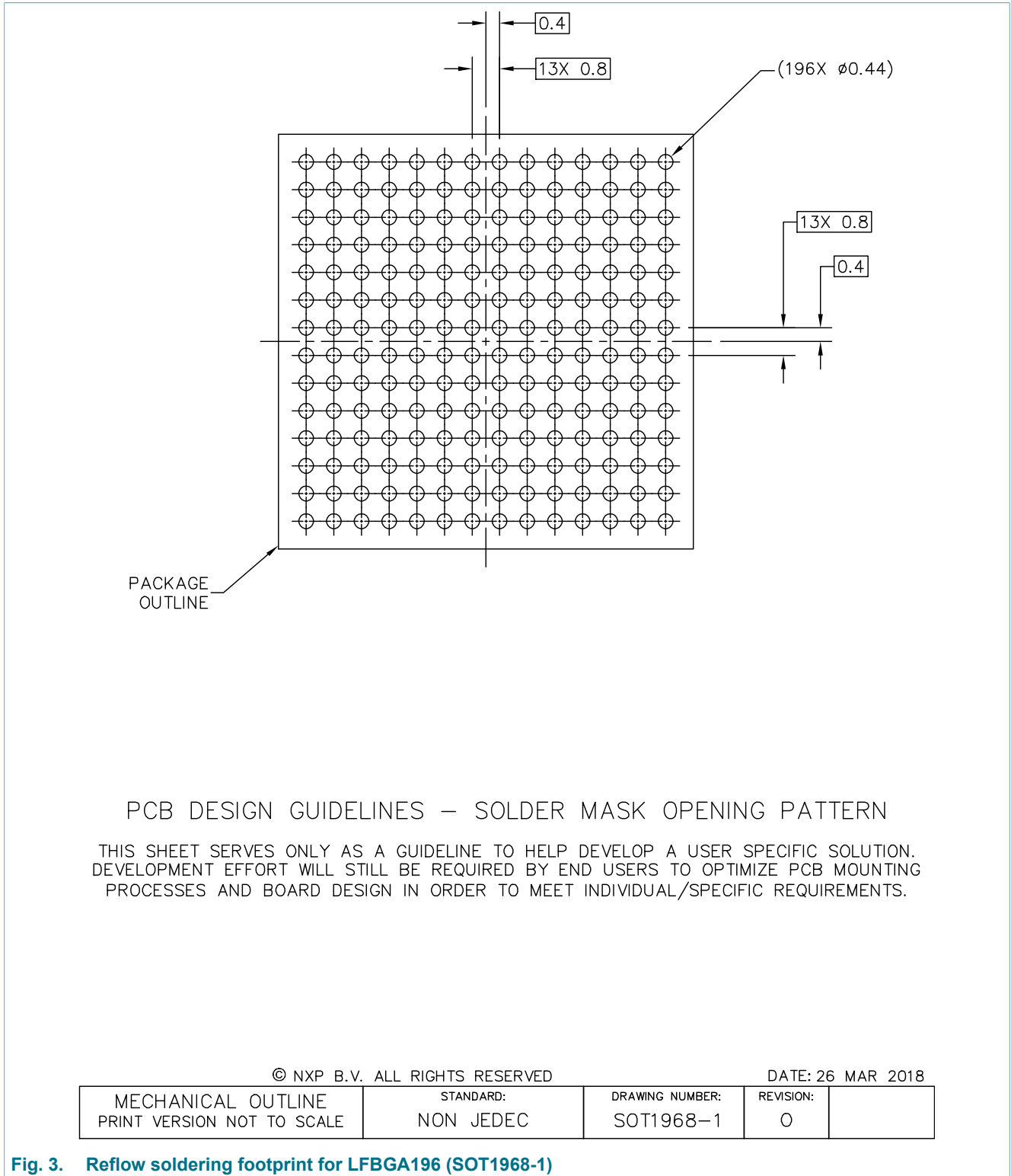
DATE: 26 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1968-1	REVISION: 0	
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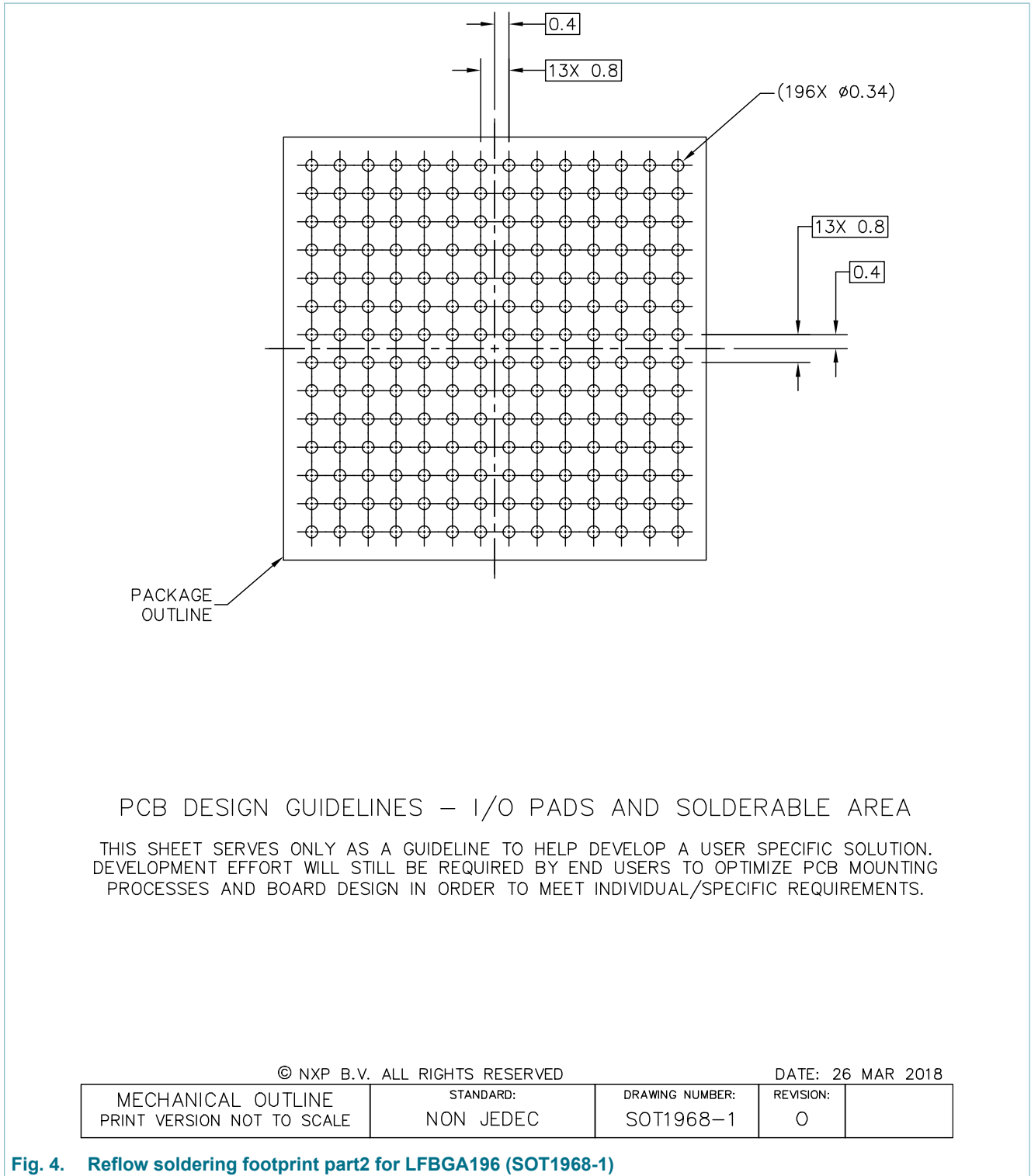
Fig. 2. Package outline LFBGA196 (SOT1968-1)

LFBGA196, low profile fine pitch ball grid array, 196 terminals, 0.8 mm pitch, 12 mm x 12 mm x 1.37 mm body

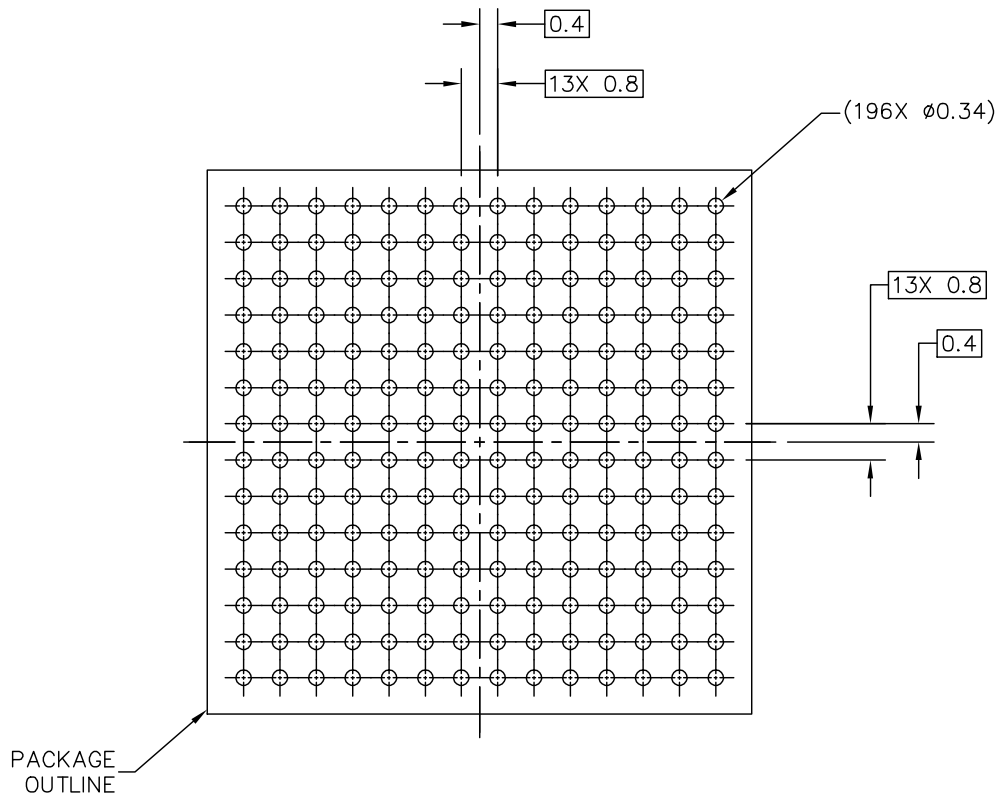
3. Soldering



LFBGA196, low profile fine pitch ball grid array, 196 terminals, 0.8 mm pitch, 12 mm x 12 mm x 1.37 mm body



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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Fig. 5. Reflow soldering footprint part3 for LFBGA196 (SOT1968-1)

4. Legal information

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